

Automotive power Schottky rectifier

Features

- Negligible switching losses
- Low thermal resistance
- Avalanche capability specified
- AEC Q101 qualified
- ECOPACK[®]2 compliant component

Description

Schottky rectifier suited for switched mode power supplies and high frequency DC to DC converters.

Packaged in SMC this device is intended for use in DC/DC chargers for automotive applications.

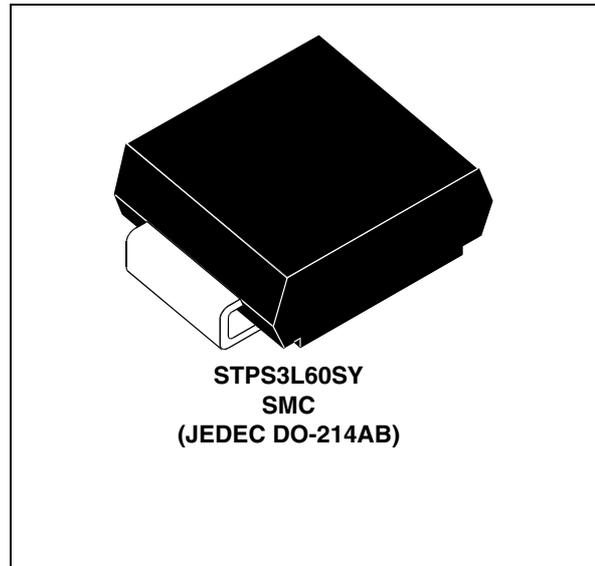


Table 1. Device summary

$I_{F(AV)}$	3 A
V_{RRM}	60 V
$T_{j(max)}$	150 °C
$V_F(max)$	0.65 V

1 Characteristics

Table 2. Absolute ratings (limiting values)

Symbol	Parameter	Value	Unit
V _{RRM}	Repetitive peak reverse voltage	60	V
I _{F(RMS)}	Forward rms current	10	A
I _{F(AV)}	Average forward current	T _C = 100 °C δ = 0.5	3
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms Sinusoidal	75
I _{RRM}	Repetitive peak reverse current	t _p = 2 μs square F=1 kHz	1
P _{ARM}	Repetitive peak avalanche power	t _p = 1 μs T _j = 25 °C	1600
T _{stg}	Storage temperature range	-65 to +175	°C
T _j	Operating junction temperature range ⁽¹⁾	-40 to +150	°C
dV/dt	Critical rate of rise reverse voltage	10000	V/μs

1. $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistances

Symbol	Parameter	Value	Unit
R _{th(j-l)}	Junction to leads	20	°C/W

Table 4. Static electrical characteristics

Symbol	Parameter	Tests conditions	Min.	Typ.	Max.	Unit
I _R ⁽¹⁾	Reverse leakage current	T _j = 25 °C	V _R = V _{RRM}		55	μA
		T _j = 125 °C		10	15	mA
V _F ⁽¹⁾	Forward voltage drop	T _j = 25 °C	I _F = 3 A		0.7	V
		T _j = 125 °C	I _F = 3 A	0.56	0.65	
		T _j = 25 °C	I _F = 6 A		0.94	
		T _j = 125 °C	I _F = 6 A	0.67	0.76	

1. Pulse test: t_p = 380 μs, δ < 2%

To evaluate the conduction losses use the following equation:

$$P = 0.54 \times I_{F(AV)} + 0.037 \times I_{F(RMS)}^2$$

Figure 1. Average forward power dissipation versus average forward current

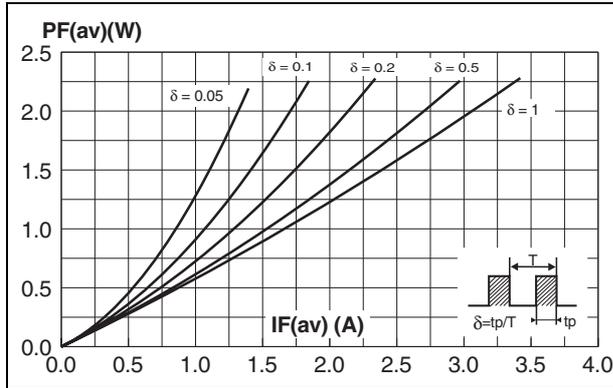


Figure 2. Average forward current versus ambient temperature (delta = 0.5)

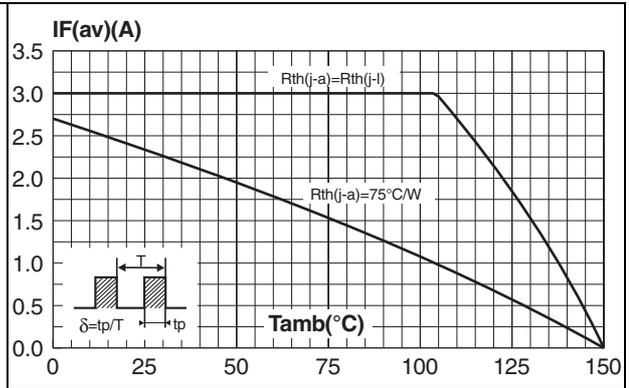


Figure 3. Normalized avalanche power derating versus pulse duration

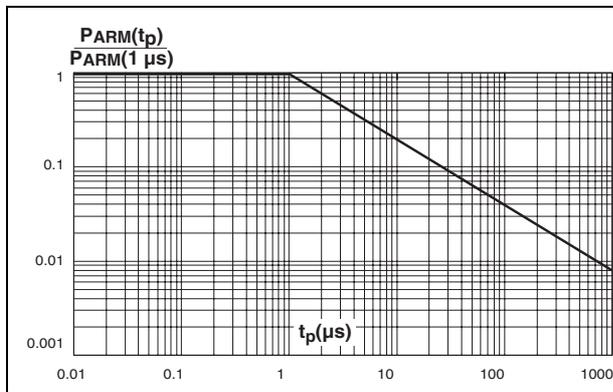


Figure 4. Normalized avalanche power derating versus junction temperature

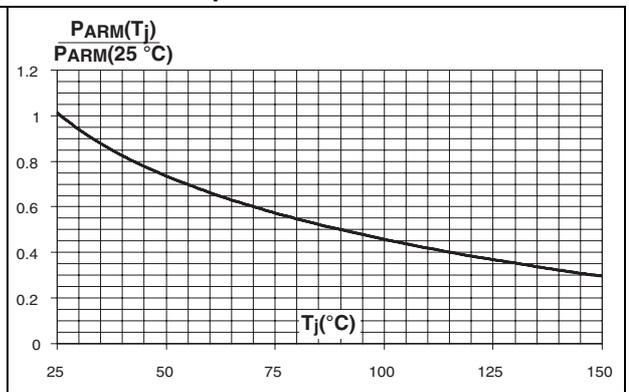


Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values)

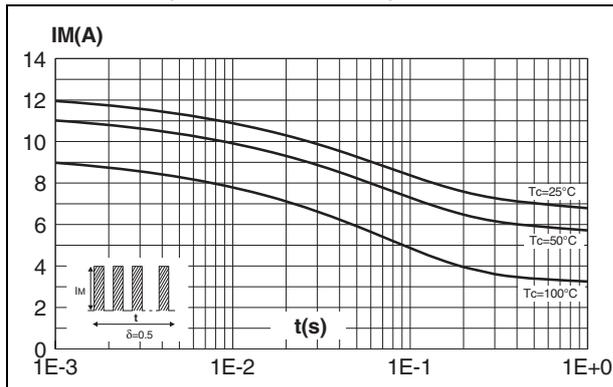


Figure 6. Relative variation of thermal impedance junction to lead versus pulse duration

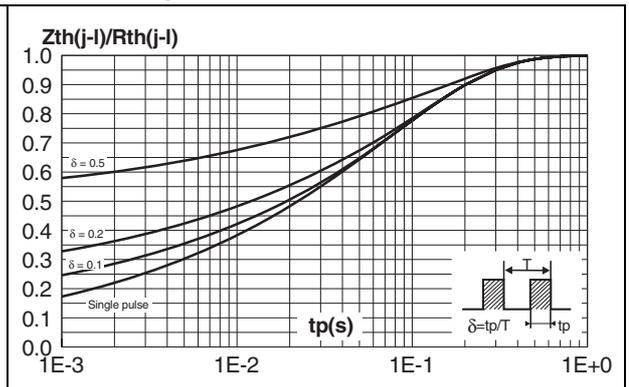


Figure 7. Reverse leakage current versus reverse voltage applied (typical values)

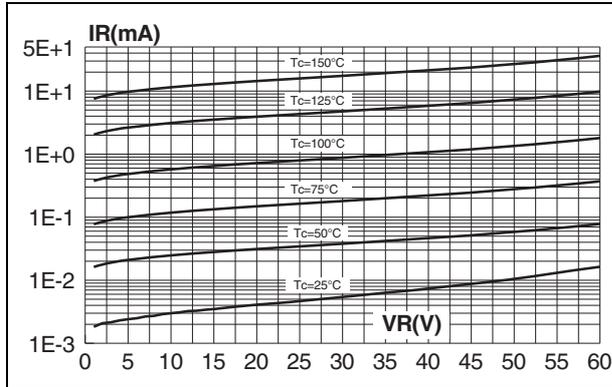


Figure 8. Junction capacitance versus reverse voltage applied (typical values)

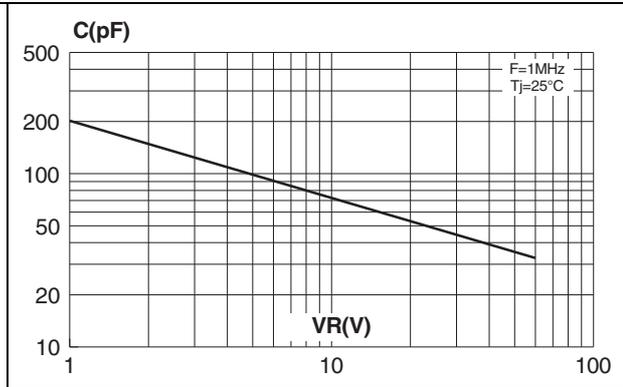


Figure 9. Forward voltage drop versus forward current (low level, maximum values)

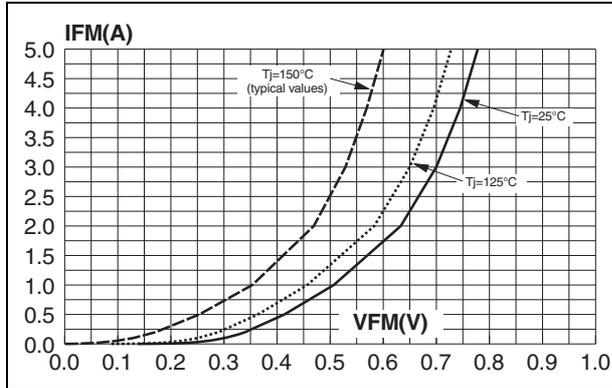


Figure 10. Forward voltage drop versus forward current (high level, maximum values)

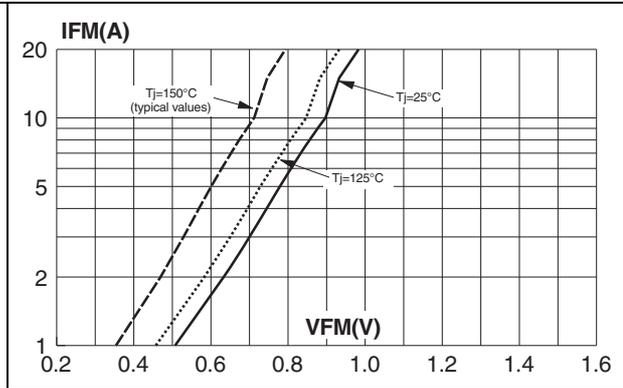
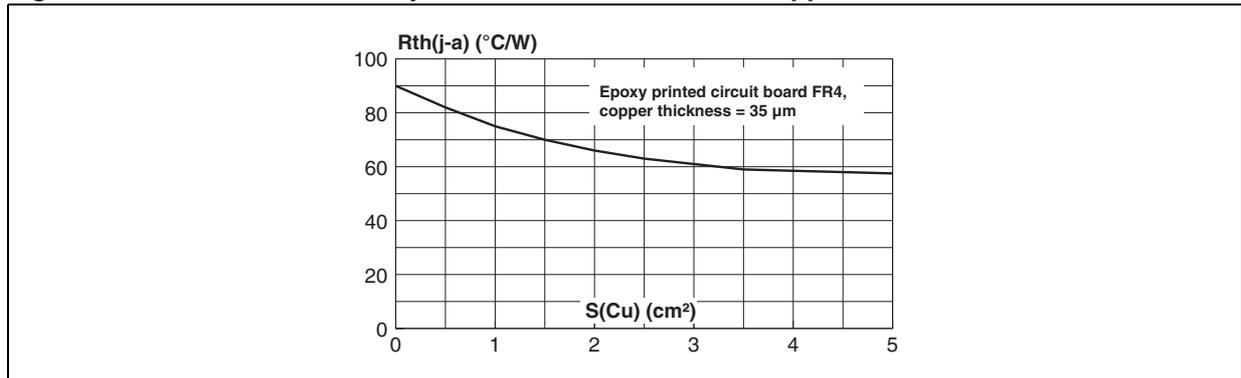


Figure 11. Thermal resistance junction to ambient versus copper surface under each lead



2 Package information

- Epoxy meets UL94,V0
- Lead-free package

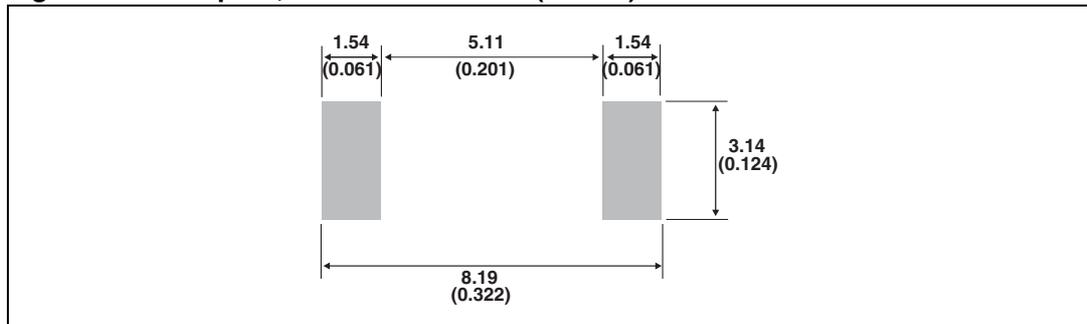
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Table 5. SMC Dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b ⁽¹⁾	2.90	3.20	0.114	0.126
c ⁽¹⁾	0.15	0.40	0.006	0.016
D	5.55	6.25	0.218	0.246
E	7.75	8.15	0.305	0.321
E1	6.60	7.15	0.260	0.281
E2	4.40	4.70	0.173	0.185
L	0.75	1.50	0.030	0.059

1. Dimensions b and c apply to plated leads

Figure 12. Footprint, dimensions in mm (inches)



3 Ordering information

Table 6. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS3L60SY	S36Y	SMC	0.24 g	2500	Tape and reel

4 Revision history

Table 7. Document revision history

Date	Revision	Changes
15-Sep-2011	1	Initial release.

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